

## **AMENDMENTS TO THE CLAIMS**

The following listing of claims will replace all prior versions and listings of claims in the application.

### **LISTING OF CLAIMS**

1. – 4. (Cancelled)

5. (Currently Amended) A device for forming a wiring, comprising:  
a liquid drop ejecting device for ejecting liquid drops onto a substrate by scanning  
on the substrate in at least first and second scanning movements; and

a surface-treatment device for surface-treating the substrate,

wherein the device for forming a wiring ejects the ejected liquid drops are  
disposed on the substrate such that a predetermined regular intervals is disposed  
between each pair of ejected liquid drops are formed therebetween in the first scanning  
movement, the predetermined interval being twice a diameter of the previously-ejected  
liquid drop or less,

the liquid drops ejected in the second scanning movement are disposed to fill the  
predetermined regular intervals, and

the substrate is surface-treated by the surface treatment device so that a contact  
angle of the ejected liquid drops with respect to the substrate is in a predetermined  
range.

6. (Previously Presented) A device for forming wiring according a wiring  
according to Claim 5, wherein the contact angle is in a range of 15° to 45°.

7. – 15. (Cancelled)

16. (Previously Presented) A device for forming wiring according to Claim 5, wherein the predetermined regular intervals are determined by controlling: a relative speed of the liquid drop ejecting device with respect to the substrate; and a frequency of the ejection by the liquid drop ejecting device.